## **APPLICATION DATA SHEET**

Electronic Version v14

Stylesheet Version v14.0

Title of Invention

METHOD OF IMPROVING ALIGNMENT FOR SEMICONDUCTOR

**FABRICATION** 

Application Type: regular, utility NTCP0030USA Attorney Docket Number:

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as our attorney(s) or agent(s) to prosecute the application identified above, and to transact all business in the United States Patent and Trademark Office connected therewith.